

Innovation through experience

Versatile application

Stanna-Q[®] is an engineered solution for the production of quad flat, no lead components.

Because Stanna-Q[®] is an electroless process bussing for electrolytic connection does not need to be engineered into the strip or carrier.

The singulation process necessitates an optimized pretreatment and active bath to ensure total flank coverage. The process is specifically developed to cope with both dicing and punching singulation methods.

Stanna-Q[®] is guaranteed to produce 3 dimensional solder joints resulting in maximum reliability in the field and yields in production.

Process compatibility

- Compatible with Eftec (Cu-Cr) or C194 (Cu-Fe)
- Vertical and horizontal processing
- Vertical barrel plating for singulated QFNs

Reliable QFN production using immersion tin

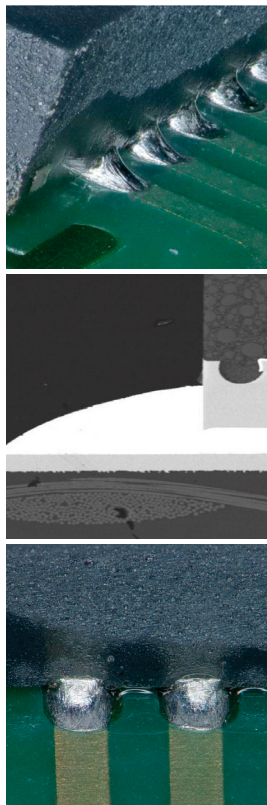


Figure 1-3:
Stanna-Q® performance
advantages

Excellent 3D solder joints

Optimized pre-treatment designed to facilitate 3D solder fillets by overcoming the impact of dicing or stamping.

Non wetted flanks will result in 2D solder joints and corrosion to the exposed copper. Immersion tin is second to none with regards to corrosion resistance.

Convincing processing advantages

MKS' Atotech extensive experience in horizontal plating is employed to make a highly productive process with maximum yields.

Phantom failures caused by exposed copper in the AOI process are a thing of the past. Electrolytic bussing can be designed out of the carrier.

Superior processing speed and rinseability lend them selves to savings in processing and reliability.

Features and benefits

- Good solderability even after steam age test
- High tin thickness >1.4 μm possible
- Stable process and quality
- Can be applied in horizontal, vertical and barrel plating mode
- Improvement of AOI inspection
- Increasing solder joint reliability
- Enhancing corrosion resistant
- Special pretreatment
- Post dip for excellent performance over lifetime

